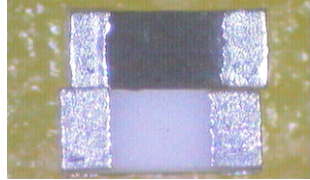


MATERIAL DECLARATION SHEET



Material Number	CR0201-LF			
Product Line	Chip Resistors			
Compliance Date	2010/08/16			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	ceramic	0.00014	Aluminum oxide	1344-28-1	96%	78.78%	82.06%
				Silicon dioxide	14808-60-7	4%	3.28%	
2	Conductor Layer	conductor glass	0.0000062	Silver	7440-22-4	96%	3.44%	3.62%
				Bismuth trioxide	1304-76-3	1%	0.045%	
				Barium oxide	1304-28-5	1%	0.045%	
				Silicon dioxide	7631-86-9	1%	0.045%	
				Boron oxide	1303-86-2	1%	0.045%	
3	Resistive Element	resistor glass	0.0000028	Ruthenium dioxide	12036-10-1	25%	0.41%	1.62%
				Silver	7440-22-4	40%	0.65%	
				Palladium	7440-05-3	15%	0.24%	
				Lead oxide glass	1317-36-8	20%	0.32%	
4	Over Coating	epoxy	0.000003	Epoxy	29690-82-2	100%	2.00%	2%
5	End Terminal	nickel chromium	0.0000006	Nickel	7440-02-0	80%	0.28%	0.35%
				Chromium III	7440-47-3	20%	0.07%	
6	Ni Plating	nickel	0.0000096	Nickel	7440-02-0	100%	5.47%	5.47%
7	Sn Plating	tin	0.0000086	Tin	7440-31-5	100%	4.88%	4.88%
		Total weight	0.0001708					

MATERIAL DECLARATION SHEET

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This Document was updated on: 05.18.2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 5 – lead in glass ... of ... electronic components.